Laird TECHNOLOGIES

Innovative **Technology** for a **Connected** World

Tflex™ HR600 Series
Thermal Gap Filler



Mid-Performance Gap Filler with 3 W/mK

Tflex™ HR600 is a cost-effective and compliant gap filler thermal interface material with excellent thermal performance and great handling for mass-production applications.

The low modulus interface pad conforms to component topography, resulting in little stress on the components, mating chassis or parts. The softness relieves mechanical stress from high stack-up tolerance and absorbs shock, resulting in improved device reliability. Tflex HR600's recovery properties for applications requiring material rework result in continued mechanical integrity even after device rework and re-assembly.

Tflex HR600 is naturally tacky on both sides and requires no additional adhesive coating to inhibit thermal performance. The tack is designed to hold the pad in place during assembly and component transport.

Tflex HR600 is electrically insulating, stable from -45ºC thru 200ºC, and meets UL 94V0 flame rating.

Features and Benefits

- Thermal conductivity 3 W/mK
- Soft and compliant
- Available in thicknesses from 0.010" thru 0.200" (0.25mm thru 5.0mm)
- Naturally tacky for adhesion during assembly and transport

Applications

- Cooling components to chassis, frame, or other mating components
- Memory modules
- Home and small office network equipment
- Mass storage devices
- Automotive electronics
- Telecommunication hardware
- Radios
- LED solid state lighting
- Power electronics
- LCD and PDP flat panel TV
- Set top boxes
- Audio and video components
- IT infrastructure
- GPS navigation and other portable devices

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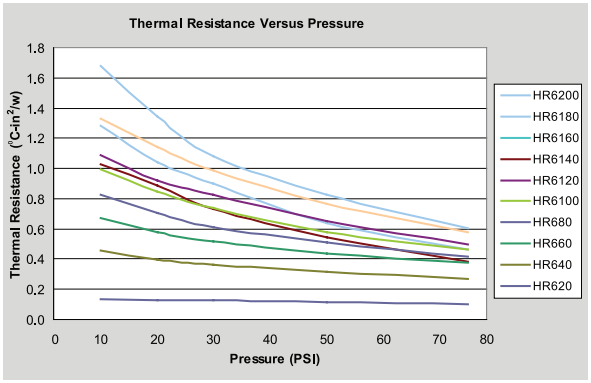
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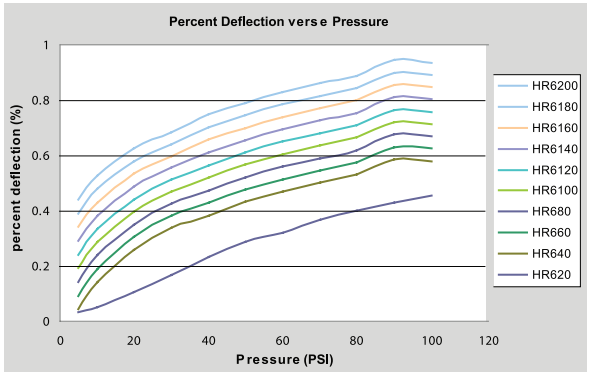
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Tflex™ HR600 Typical Properties

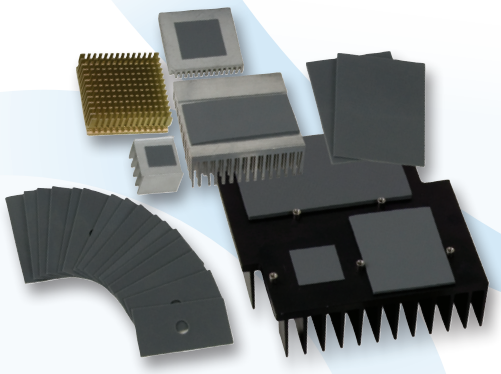
	Tflex™ HR600	Test Method
Construction	Filled silicone elastomer	NA
Color	Dark Grey	Visual
Thermal conductivity	3 W/mK	ASTM D5470
Hardness (Shore 00)	40 (at 3 second delay)	ASTM D2240
Density	2.5 g/cc	Helium Pyncometer
Thickness range	0.010" - .200" (0.25 - 5.0mm)	
Thickness tolerance	±10%	
UL flammability rating	94 V0	UL
Temperature range	-45°C to 200°C	NA
Volume resistivity	10 ^13 ohm-cm	ASTM D257
Outgassing TML	0.19%	ASTM E595
Outgassing CVCM	0.07%	ASTM E595
Coefficient Thermal Expansion (CTE)	217 ppm/C	IPC-TM-650 2.4.24





Standard Thicknesses
0.010-inch to 0.200-inch (0.25 to 5.0 mm)
0.010-inch and 0.015-inch thick materials come standard with fiberglass reinforcement designated by the suffix "FG"

Options
Proprietary DC1 option available to eliminate tack from one side to aid in handling.



Material Name and Thickness
Tflex™ indicates elastomeric gap filler product line
HR6xxx indicates high recovery '6 series' 3 W/mK material
FG desginates Fiberglass (available in 0.010 and 0.015-inch thickness only)
DC1 designates proprietary option eliminating tack from one side

Examples
Tflex™ HR6120 = 0.120-inch thick material
Tflex™ HR610FG = 0.010-inch thick material with fiberglass reinforecement
Tflex™ HR6120-DC1 = 0.120-inch thick material with proprietary DC1 option

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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